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## **Optoscribe reaches multi-million-pound agreement to supply optical interconnect to global Tier 1 supplier**

Optoscribe says it has reached a multi-million-pound procurement agreement to supply transceiver optical interconnect chips, in volume, to a global Tier 1 optical networking supplier. The supplier, whose name Optoscribe has not revealed, will use the interconnect chips for its photonic integration projects to meet increasing data center interconnect market needs, the company says.

Optoscribe, which makes glass-based integrated photonics components, will provide an array of components incorporated into one monolithic glass chip, enabling the customer to accelerate its product to volume manufacturing.

Using laser direct write technology, Optoscribe manufactures glass-based integrated photonic components for the telecommunications and data communications markets. The company primarily serves high volume optical transceiver manufacturers.

Founded in 2010 out of Heriot Watt University, Optoscribe also has experience with multicore fiber applications (see "Optoscribe unveils eight-channel multicore fiber fanout device").

"This agreement is great news for the company and further endorses our unique 3D glass waveguide interface technology that enables simple coupling of fiber to active elements such as arrays of lasers and photodiodes in optical transceivers," said Nick Psaila, Optoscribe's chief executive officer. "This contract underpins our commitment to component manufacturing for the data center market, and we are well placed to grow rapidly in line with demand."

The Livingston, UK company closed £1.8 million (\$2.3 million) in Series B funding for the purpose of rapid expansion, as well as product supply, in June of 2017 (see "Optoscribe closes \$2.3 million Series B funding round").

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